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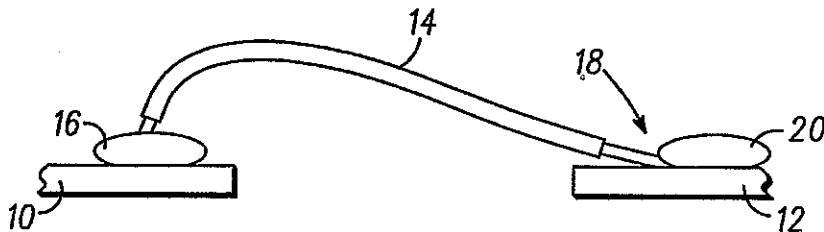
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(54) Title: WIREBONDING INSULATED WIRE



(57) Abstract: An electrical connection for connecting a bond pad of a first device and a bond pad of a second device with an insulated or coated wire. The electrical connection includes a first wirebond securing a first portion of the insulated bond wire to the first device bond pad. A second wirebond secures a second portion of the insulated bond wire to the second device bond pad. A bump is formed over the second wirebond, and the bump is offset from the second wirebond. The offset bump enhances the second bond, providing it with increased wire peel strength.

vice bond pad. A bump is formed over the second wirebond, and the bump is offset from the second wirebond. The offset bump enhances the second bond, providing it with increased wire peel strength.